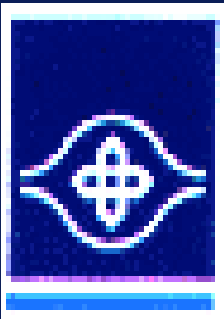

2020 Operation Briefing of Nan Ya PCB Corp.

March 4th 2021



Disclaimer

The description of historical events might include the information that was not reviewed by accountants. Thus, it might be insufficient to fully exhibit the financial status or operation results of Nan Ya PCB Corp.

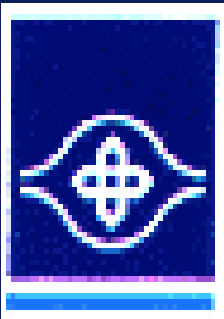
The actual operation results, financial status, and sales outlook in the future might be different from what will be indicated or implied in this meeting. The reasons may be including but not limited to the market demand, price fluctuation, competition dynamic, global economy, supply-chain, foreign exchange rate, and other risks that the Company cannot control.

Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.



Agenda

- **Company Profile**
- **Financial Status**
- **Future Product Development**
- **Operational Goals**



Company Profile

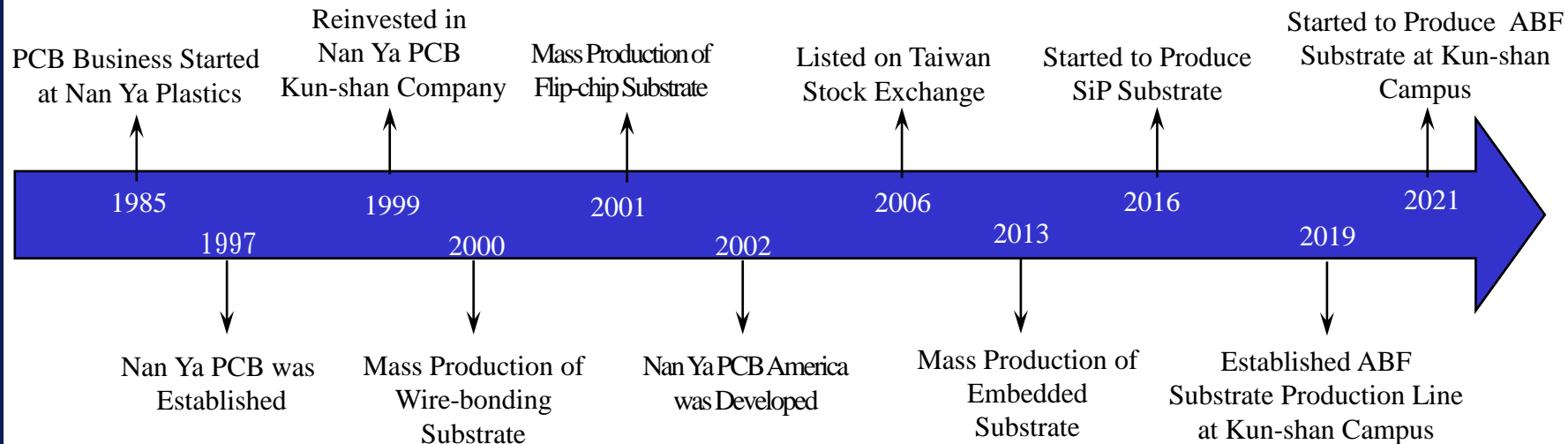
Business Overview

- **Subsidiary Company of Nan Ya Plastics Corp.**
- **Manufacture and Sell PCBs and IC Substrates**
- **2020 Consolidated Revenues: NTD 38.5 Billion**
- **Market Value: NTD 117.6 Billion(December 31st 2020)**
- **Production Locations : Taiwan and China**



Company Profile

Milestone



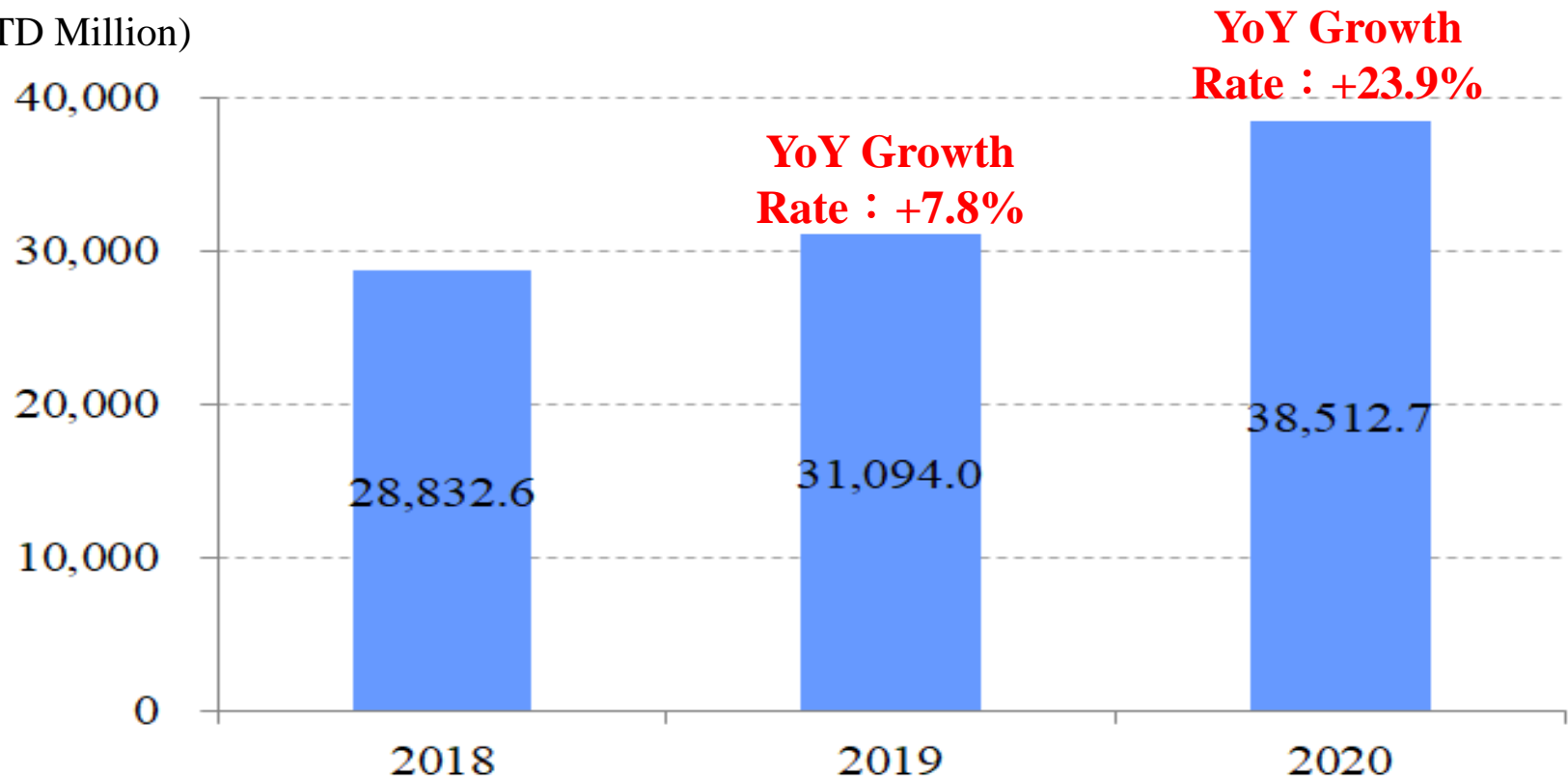
- **1985 : PCB business unit was formed at Nan Ya Plastics Corp. and started manufacturing PCBs**
- **1997 : Approved by the Board of Nan Ya Plastics, Nan Ya PCB Corp. was established via reinvestment**
- **1999 : Reinvested Nan Ya PCB Kun-shan Company with capital of USD29.8 million**
- **2000 : Started manufacturing wire-bonding substrates**
- **2001 : Upgraded technologies and produced flip-chip substrates**
- **2002 : Established Nan Ya PCB America Corp.**
- **2006 : Listed on Taiwan Stock Exchange with ticker 8046 TT**
- **2013 : Upgraded technologies and produced Embedded substrates**
- **2016 : Started to produce System in Package (SiP) substrates**
- **2019 : In response to market demand, Nan Ya PCB Corp. started to build ABF substrate production line at Kun-shan Campus**
- **2021 : Kun-shan Campus started to manufacture ABF substrates in Q1**



Financial Status

Consolidated Revenues(IFRS) in Last 3 Years

(NTD Million)



- **Revenues in 2019 were 7.8% greater than those in 2018:**

Nan Ya PCB continued to increase the sales ratio of high-value products, enabling the average selling price to rise. The revenues in 2019 kept growing from 2018.

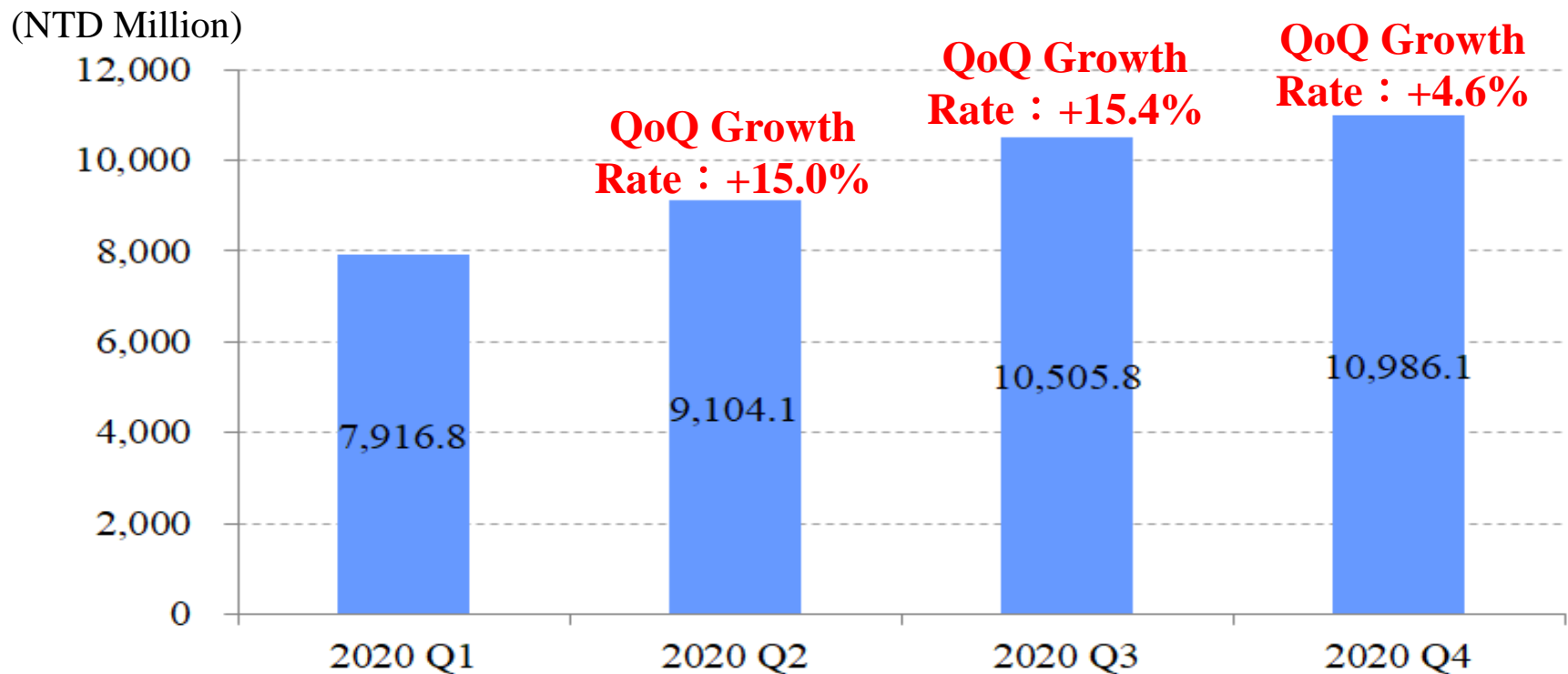
- **Revenues in 2020 were 23.9% greater than those in 2019:**

Nan Ya PCB was an early entrant in high-end telecom and SiP substrate fields and benefited from the increase in customer demands, and the 2020 revenues grew significantly from 2019.



Financial Status

Quarterly Consolidated Revenues(IFRS) in 2020

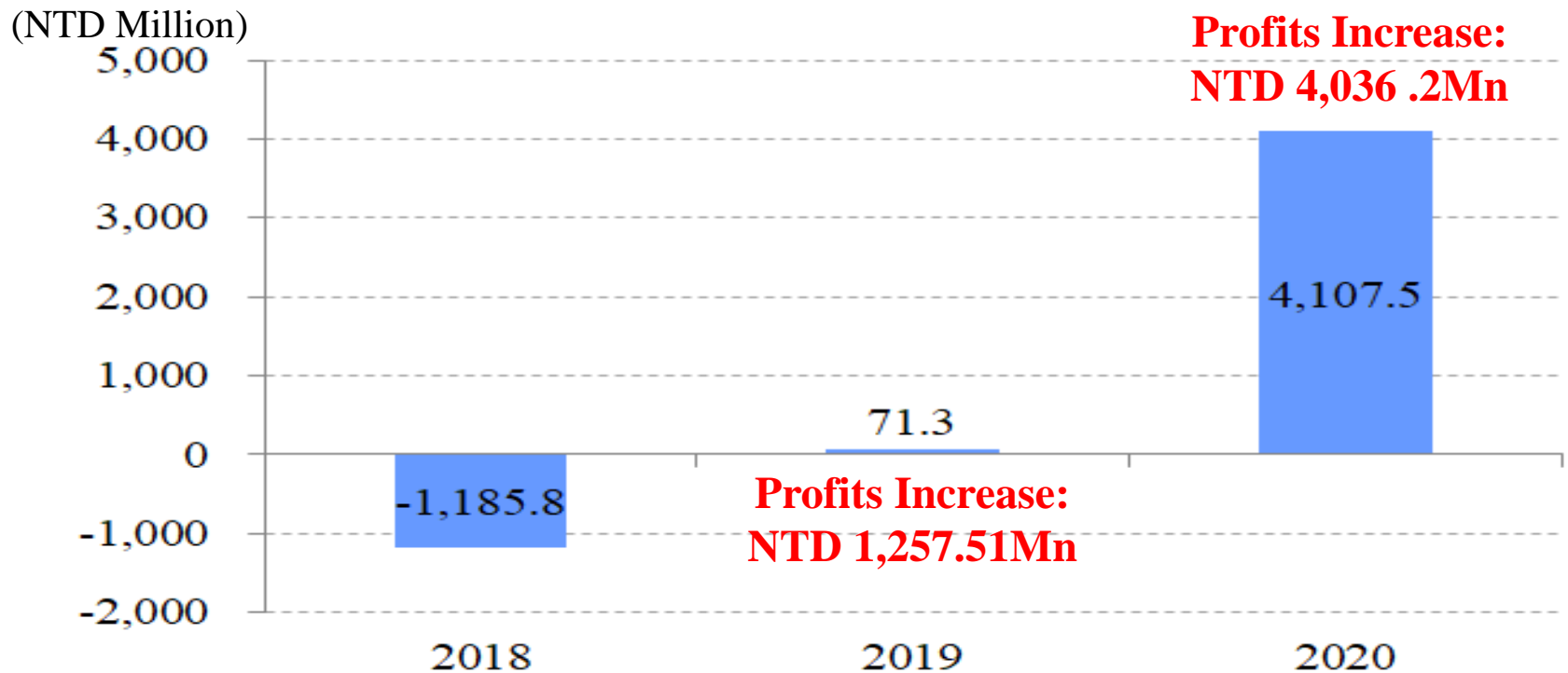


- **Revenues in 20Q2 were 15.0% greater than those in 20Q1:**
Because the impacts COVID-19 faded, the 20Q2 sales grew 15.0% from 20Q1.
- **Revenues in 20Q3 were 15.4% greater than those in 20Q2:**
Helped by rising demands in telecom and consumer electronics, 20Q3 sales kept growing.
- **Revenues in 20Q4 were 4.6% greater than those in 20Q3:**
Increasing demands in the PC, telecom, and automotive electronics boosted the Q4 revenues and achieved our goal, consecutive growth of quarterly revenues.



Financial Status

Operation Profits(Losses) in Last 3 Years



- **Operation profits in 2019 were increasing NTD 1,257.1 Mn from 2018:**

The sales ratio of high-layer counts and large body size telecom substrates increased and turned the 2019 operation profits of Nan Ya PCB in black ink.

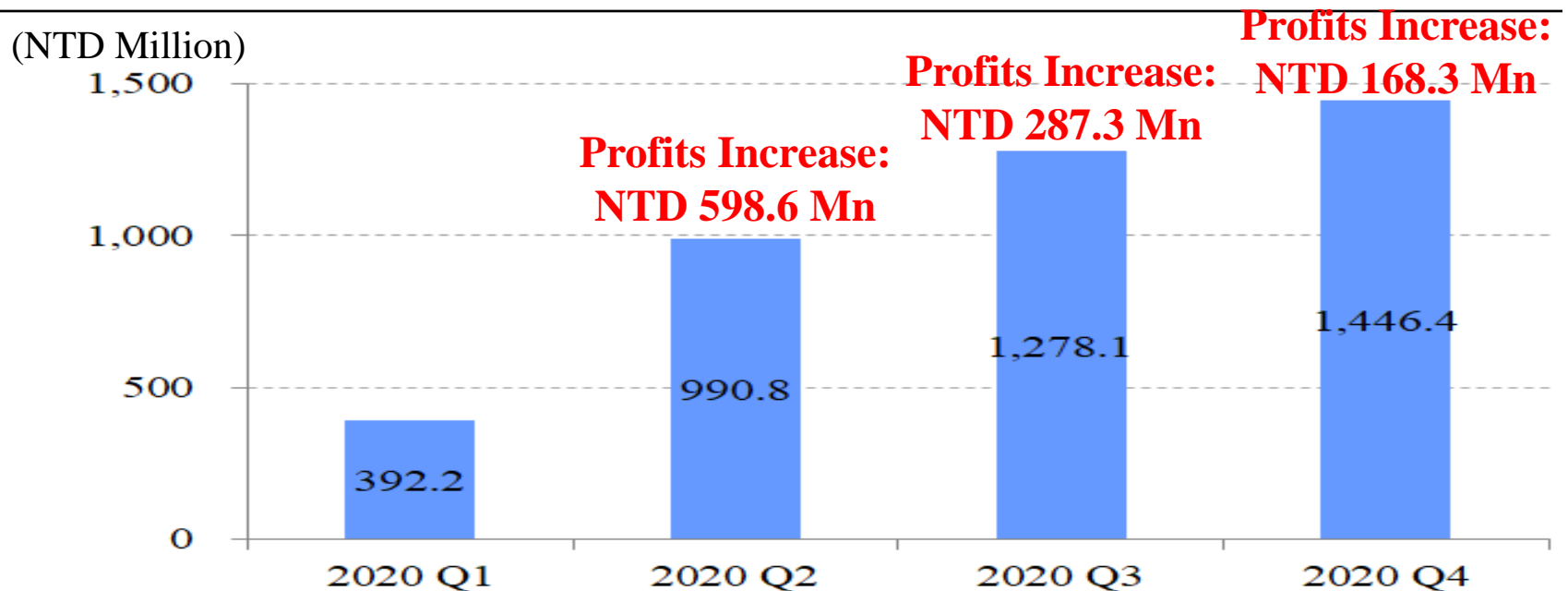
- **Operation profits in 2020 were increasing NTD 4,036.2 Mn from 2019:**

Through manufacturing process enhancements to improve yield rate and better product mix due to rising sales of high-end telecom and SiP products, the 2020 operation profits grew significantly.



Financial Status

Quarterly Operation Profits in 2020

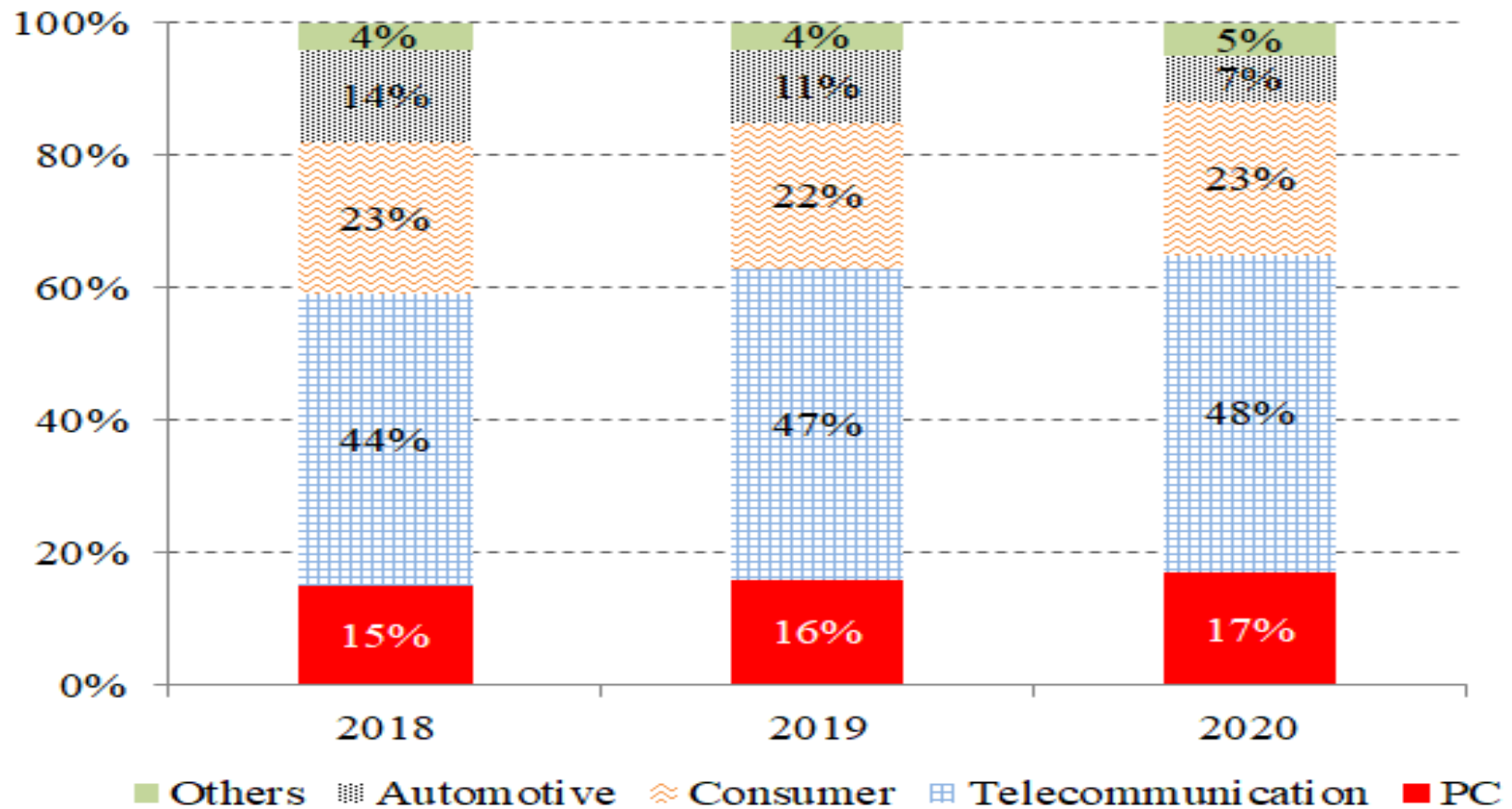


- **Operation profits in 20Q2 were increasing NTD 598.6 Mn from 20Q1:**
With better demands in high-end IC substrates, 20Q2 profits grew from 20Q1.
- **Operation profits in 20Q3 were increasing NTD 287.3 Mn from 20Q2:**
The 20Q3 operation profits were greater than 20Q2 because of increasing sales in high value products such as high-end telecom substrates, SiP substrates and interposers.
- **Operation profits in 20Q4 were increasing NTD 168.3 Mn from 20Q3:**
Aside from increasing demands in high-end telecom substrates, rising sales of notebook PCs, game consoles, automotive electronics, and etc. also lifted 20Q4 operation profits, which met our target, consecutive quarterly operation profits growth.



Financial Status

Revenue Structure(By Applications)

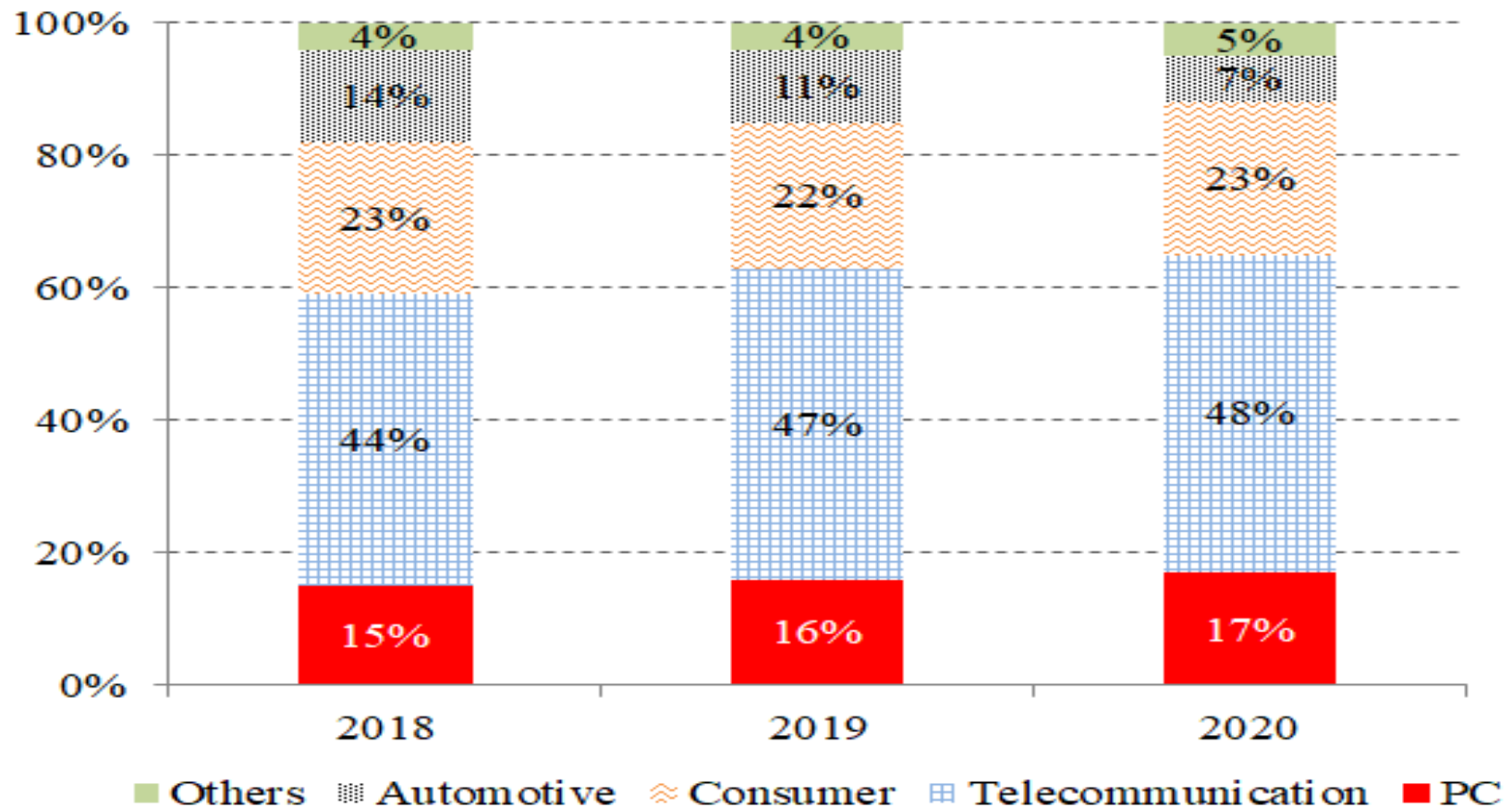


- Because of better demands in PCs and telecom products driven by work from home, related revenue ratios grew from 2019.
- Benefited by the rising demands in true wireless studio and new generation game consoles, our revenue ratio of consumer electronics products has grown.



Financial Status

Revenue Structure(By Applications)



- The COVID-19 severely impacted the car sales in the 20H1 and led to our declining automotive revenue ratio, despite of the resuming demands in 20H2.
- Nan Ya PCB actively explored the AI and HPC fields and successfully gained more high value orders from those areas. Thus, the revenue ratio of others continued to grow.



Future Product Development

Continue to Expand High Value Products

■ High-end ABF Substrate

In 2021, not only will we continue to plow high-end telecom markets, but also expand our market share in AI and HPC products. Additionally, the demands in work from home and stay at home economics are expected to grow, and we will keep producing substrates for high-end processors and graphic chips to further enlarge our market share.

■ SiP(System in Package) Substrate

Given the trend of heterogeneous integration remains, SiP technologies will be applied to all sorts of mobile device. We will continue to produce SiP substrates for new generation wearable device and camera modules in high-end smartphones. Also we will evaluate our capacities to penetrate the antenna in package modules. Our SiP substrate sales are expected to grow.

■ HDI

As the designs of handset, consumer electronics, and automotive electronics are becoming sophisticated, the consumption of high value HDI is increasing. Thus, we will roll out HDI for new generation memories, solid state drive, and infotainment systems to meet the growing demands in notebook PCs and automobiles to boost our profits.



Operational Goals

The Company Seeks Continuous Operation Profits Growth

■ Profits in 21H1 is expected to grow

With the help by the solid demands in PCs, telecom, and automotive electronics, our sales performance is expected to beat the seasonality. Also, our new high-end IC substrate capacities will be available in 21Q1 and reaching 100% utilization rate in 21Q2 to achieve our goal of 100% production and sales, and spur revenues and profits. Additionally, we apply AI to our manufacturing management to improve yield rate and lower production costs. With the synergy of the hardware and software, our 21H1 profits are expected to grow annually.

■ To Seek quarter on quarter profit growth in 2021

Sales Expansion: Nan Ya PCB will continue the operation strategies in 2020 to develop CPU, high-end telecom equipment, AI, HPC, and high-end automotive application substrates and PCBs. Also, we will continue to de-bottleneck to increase output and meet clients' needs.

Costs Reduction: We will continue to improve the yield rate and efficiency through strengthening manufacturing processes. Also, we will implement digital management to further enhance performance. This year, we will strive to achieve the goal of consecutive quarterly growth of our profits.



Thank You

